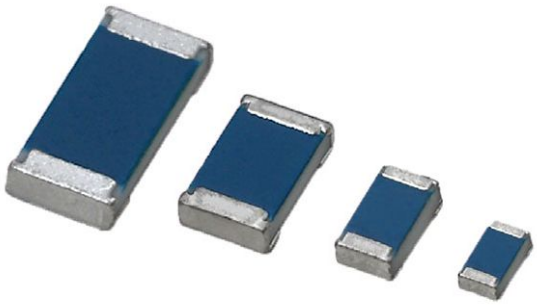
Professional Thin Film Chip Resistors



Automotive grade MC AT professional thin film chip resistors are the perfect choice for most fields of modern professional electronics where reliability and stability is of major concern. Typical applications include automotive, telecommunication, industrial, medical equipment, precision test, and measuring equipment.

FEATURES

- Operating temperature up to 175 °C
- Rated dissipation P_{85} up to 0.4 W for size 1206
- AEC-Q200 qualified
- Approved to EN 140401-801
- Advanced sulfur resistance verified according to ASTM B 809
- Superior temperature cycling robustness
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

AUTOMOTIVE GRADE

RoHS COMPLIANT

APPLICATIONS

- Automotive
- Telecommunication
- Medical equipment
- Industrial equipment

TECHNICAL SPECIFICATIONS				
DESCRIPTION	**MCS 0402 AT**	**MCT 0603 AT**	**MCU 0805 AT**	**MCA 1206 AT**
Imperial size	0402	0603	0805	1206
Metric size code	RR1005M	RR1608M	RR2012M	RR3216M
Resistance range	1 Ω to 221 kΩ; 0 Ω	1 Ω to 511 kΩ; 0 Ω	1 Ω to 1 MΩ; 0 Ω	1 Ω to 1 MΩ; 0 Ω
Resistance tolerance	± 1 %, ± 0.5 %			
Temperature coefficient	± 50 ppm/K; ± 25 ppm/K			
Rated dissipation P_{85} (1)	0.100 W	0.150 W	0.200 W	0.400 W
Operating voltage, $U_{max.}$ AC_{RMS}/DC	50 V	75 V	150 V	200 V
Permissible film temperature, $\vartheta_{F\ max.}$ (1)	175 °C			
Operating temperature range	-55 °C to 175 °C			
Internal thermal resistance (1)	90 K/W	63 K/W	38 K/W	32 K/W
Permissible voltage against ambient (insulation): 1 min; U_{ins}	75 V	100 V	200 V	300 V
Failure rate: $FIT_{observed}$	≤ 0.1 x 10^{-9}/h			

Note

(1) Please refer to APPLICATION INFORMATION below

APPLICATION INFORMATION

When the resistor dissipates power, a temperature rise above the ambient temperature occurs, dependent on the thermal resistance of the assembled resistor together with the printed circuit board. The rated dissipation applies only if the permitted film temperature is not exceeded.

Please consider the application note “Thermal Management in Surface-Mounted Resistor Applications” (www.vishay.com/doc?28844) for information on the general nature of thermal resistance.

These resistors do not feature a limited lifetime when operated within the permissible limits. However, resistance value drift increasing over operating time may result in exceeding a limit acceptable to the specific application, thereby establishing a functional lifetime.

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MAXIMUM RESISTANCE CHANGE AT RATED DISSIPATION

OPERATION MODE		STANDARD	POWER	ADVANCED TEMPERATURE
		P_{70}	P_{70}	P_{85}
Rated dissipation	MCS 0402 AT	0.063 W	0.100 W	0.100 W
	MCT 0603 AT	0.100 W	0.125 W	0.150 W
	MCU 0805 AT	0.125 W	0.200 W	0.200 W
	MCA 1206 AT	0.250 W	0.400 W	0.400 W
Operating temperature range		-55 °C to 125 °C	-55 °C to 155 °C	-55 °C to 175 °C
Permissible film temperature, $\vartheta_{F\ max.}$		125 °C	155 °C	175 °C
Max. resistance change at rated dissipation for resistance range, $\lvert\Delta R/R\rvert$ after:	MCS 0402 AT	1 Ω to 221 kΩ	1 Ω to 221 kΩ	1 Ω to 221 kΩ
	MCT 0603 AT	1 Ω to 511 kΩ	1 Ω to 511 kΩ	1 Ω to 511 kΩ
	MCU 0805 AT	1 Ω to 1 MΩ	1 Ω to 1 MΩ	1 Ω to 1 MΩ
	MCA 1206 AT	1 Ω to 1 MΩ	1 Ω to 1 MΩ	1 Ω to 1 MΩ
	1000 h	≤ 0.15 %	≤ 0.3 %	≤ 0.5 %
	8000 h	≤ 0.25 %	≤ 0.5 %	-
	225 000 h	≤ 1.0 %	-	-

Note

- The presented operation modes do not refer to different types of resistors, but actually show examples of different loads, that lead to different film temperatures and different achievable load-life stability (drift) of the resistance value. A suitable low thermal resistance of the circuit board assembly must be safeguarded in order to maintain the film temperature of the resistors within the specified limits. Please consider the application note “Thermal Management in Surface-Mounted Resistor Applications” (www.vishay.com/doc?28844) for information on the general nature of thermal resistance

TEMPERATURE COEFFICIENT AND RESISTANCE RANGE

TYPE / SIZE	TCR	TOLERANCE	RESISTANCE	E-SERIES
MCS 0402 AT	± 50 ppm/K	± 1 %	1 Ω to 221 kΩ	E24; E96
	± 25 ppm/K	± 0.5 %	10 Ω to 221 kΩ	E24; E192
	Jumper [1], $I_{max.}$ = 0.63 A	≤ 20 mΩ	0 Ω	-
MCT 0603 AT	± 50 ppm/K	± 1 %	1 Ω to 511 kΩ	E24; E96
	± 25 ppm/K	± 0.5 %	10 Ω to 511 kΩ	E24; E192
	Jumper [1], $I_{max.}$ = 1 A	≤ 20 mΩ	0 Ω	-
MCU 0805 AT	± 50 ppm/K	± 1 %	1 Ω to 1 MΩ	E24; E96
	± 25 ppm/K	± 0.5 %	10 Ω to 1 MΩ	E24; E192
	Jumper [1], $I_{max.}$ = 1.5 A	≤ 20 mΩ	0 Ω	-
MCA 1206 AT	± 50 ppm/K	± 1 %	1 Ω to 1 MΩ	E24; E96
	± 25 ppm/K	± 0.5 %	10 Ω to 1 MΩ	E24; E192
	Jumper [1], $I_{max.}$ = 2 A	≤ 20 mΩ	0 Ω	-

Note

[1] The temperature coefficient of resistance (TCR) is not specified for 0 Ω jumpers

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PACKAGING

TYPE / SIZE	CODE	QUANTITY	PACKAGING STYLE	WIDTH	PITCH	PACKAGING DIMENSIONS
MCS 0402 AT	E5	5000	Paper tape acc. IEC 60286-3, Type 1a	8 mm	2 mm	Ø 180 mm / 7"
	E0	10 000				
MCT 0603 AT	P5	5000			4 mm	Ø 180 mm / 7"
	PW	20 000				Ø 330 mm / 13"
MCU 0805 AT	P5	5000				Ø 180 mm / 7"
	PW	20 000				Ø 330 mm / 13"
MCA 1206 AT	P5	5000				Ø 180 mm / 7"

PART NUMBER AND PRODUCT DESCRIPTION

Part Number: MCT0603MD4641DPW00
Part Number: MCT0603MZ0000ZP500

M	C	T	0	6	0	3	M	D	4	6	4	1	D	P	W	0	0

TYPE / SIZE	VERSION	TCR	RESISTANCE	TOLERANCE	PACKAGING
MCS0402 **MCT0603** **MCU0805** **MCA1206**	**M** = AT (automotive)	**D** = ± 25 ppm/K **C** = ± 50 ppm/K **Z** = jumper	3 digit value 1 digit multiplier **Multiplier** **8** = $*10^{-2}$ **9** = $*10^{-1}$ **0** = $*10^{0}$ **1** = $*10^{1}$ **2** = $*10^{2}$ **3** = $*10^{3}$ **4** = $*10^{4}$ **0000** = jumper	**D** = ± 0.5 % **F** = ± 1 % **Z** = jumper	**E5** **E0** **P5** **PW**

Product Description: MCT 0603-25 0.5 % AT PW 4K64
Product Description: MCT 0603 AT P5 0R0

MCT	0603	-25	0.5 %	AT	PW	4K64
TYPE	SIZE	TCR	TOLERANCE	VERSION	PACKAGING	RESISTANCE
MCS **MCT** **MCU** **MCA**	**0402** **0603** **0805** **1206**	± **25** ppm/K ± **50** ppm/K	± **0.5 %** ± **1 %**	**AT** = automotive	**E5** **E0** **P5** **PW**	**4K64** = 4.64 kΩ **0R0** = jumper

Note

- Products can be ordered using either the PART NUMBER or the PRODUCT DESCRIPTION

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DESCRIPTION

Production is strictly controlled and follows an extensive set of instructions established for reproducibility. A homogeneous film of special metal alloy is deposited on a high grade ceramic substrate (Al_2O_3) and conditioned to achieve the desired temperature coefficient. Specially designed inner contacts are deposited on both sides. A special laser is used to achieve the target value by smoothly cutting a meander groove in the resistive layer without damaging the ceramics. The resistor elements are covered by a unique protective coating designed for electrical, mechanical and climatic protection. The terminations receive a final pure matte tin on nickel plating.

The result of the determined production is verified by an extensive testing procedure and optical inspection performed on 100 % of the individual chip resistors. This includes full screening for the elimination of products with potential risk of early field failures (feasible for $R \geq 10\ \Omega$). Only accepted products are laid directly into the paper tape in accordance with **IEC 60286-3 Type 1a** [(1)].

ASSEMBLY

The resistors are suitable for processing on automatic SMD assembly systems. They are suitable for automatic soldering using wave, reflow or vapor phase as shown in **IEC 61760-1** [(1)]. The encapsulation is resistant to all cleaning solvents commonly used in the electronics industry, including alcohols, esters and aqueous solutions. The suitability of conformal coatings, potting compounds and their processes, if applied, shall be qualified by appropriate means to ensure the long-term stability of the whole system.

The resistors are RoHS-compliant; the pure matte tin plating provides compatibility with lead (Pb)-free and lead-containing soldering processes. Solderability is specified for 2 years after production or requalification. The permitted storage time is 20 years. The immunity of the plating against tin whisker growth has been proven under extensive testing.

MATERIALS

Vishay acknowledges the following systems for the regulation of hazardous substances:

- IEC 62474, Material Declaration for Products of and for the Electrotechnical Industry, with the list of declarable substances given therein [(2)]
- The Global Automotive Declarable Substance List (GADSL) [(3)]
- The REACH regulation (1907/2006/EC) and the related list of substances with very high concern (SVHC) [(4)] for its supply chain

The products do not contain any of the banned substances as per IEC 62474, GADSL, or the SVHC list, see www.vishay.com/how/leadfree.

Hence the products fully comply with the following directives:

- 2000/53/EC End-of-Life Vehicle Directive (ELV) and Annex II (ELV II)
- 2011/65/EU Restriction of the Use of Hazardous Substances Directive (RoHS) with amendment 2015/863/EU
- 2012/19/EU Waste Electrical and Electronic Equipment Directive (WEEE)

Vishay pursues the elimination of conflict minerals from its supply chain, see the Conflict Minerals Policy at www.vishay.com/doc?49037.

APPROVALS

The resistors are approved within the IECQ-CECC Quality Assessment System for Electronic Components to the detail specification **EN 140401-801** which refers to **EN 60115-1**, **EN 60115-8** and the variety of environmental test procedures of the **IEC 60068** [(1)] series. The detail specification refers to the climatic categories 55/125/56, which relates to the "standard operation mode" of this datasheet.

Conformity is attested by the use of the **CECC** logo ( ) as the mark of conformity on the package label.

The resistors are qualified according to AEC-Q200.

Vishay Beyschlag has achieved **"Approval of Manufacturer"** in accordance with **IECQ 03-1**. The release certificate for **"Technology Approval Schedule"** in accordance with **CECC 240001** based on **IECQ 03-3-1** is granted for the Vishay Beyschlag manufacturing process.

RELATED PRODUCTS

For more information about products with better TCR and tighter tolerance please refer to the **MC AT - Precision** datasheet (www.vishay.com/doc?28785).

Chip resistor arrays may be used in sensing applications or precision amplifiers where close matching between multiple resistors is necessary. Please refer to the **ACAS AT - Precision** datasheet (www.vishay.com/doc?28770).

MC AT series is also available with gold termination for conductive gluing: **MC ATAU - Precision**. Please refer to the datasheet (www.vishay.com/doc?28877).

For high power and high temperature applications **MCW AT** wide terminal thin film chip resistors offer extremely high power ratings and extraordinary temperature cycling robustness.

Please refer to the datasheets for
precision (www.vishay.com/doc?28847) and
professional (www.vishay.com/doc?28796) specification.

These wide-terminal products are also available in low-ohmic values, **NCW AT** (www.vishay.com/doc?28849).

Notes

(1) The quoted IEC standards are also released as EN standards with the same number and identical contents
(2) The IEC 62474 list of declarable substances is maintained in a dedicated database, which is available at http://std.iec.ch/iec62474
(3) The Global Automotive Declarable Substance List (GADSL) is maintained by the American Chemistry Council and available at www.gadsl.org
(4) The SVHC list is maintained by the European Chemical Agency (ECHA) and available at http://echa.europa.eu/candidate-list-table

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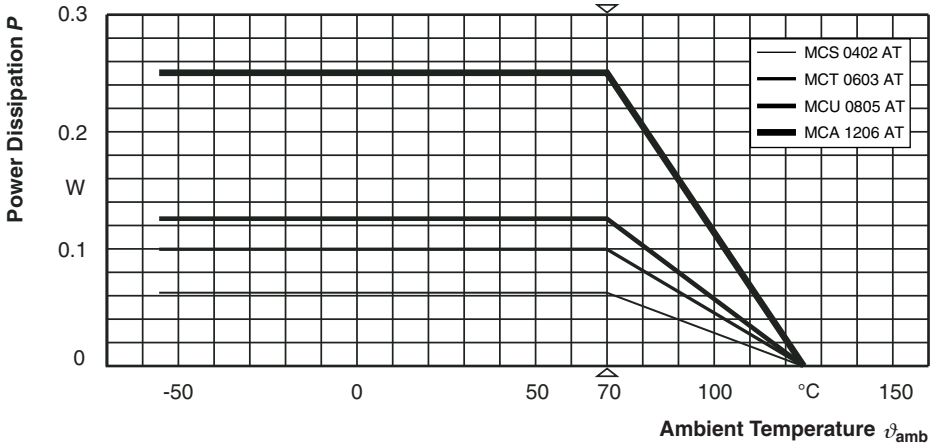
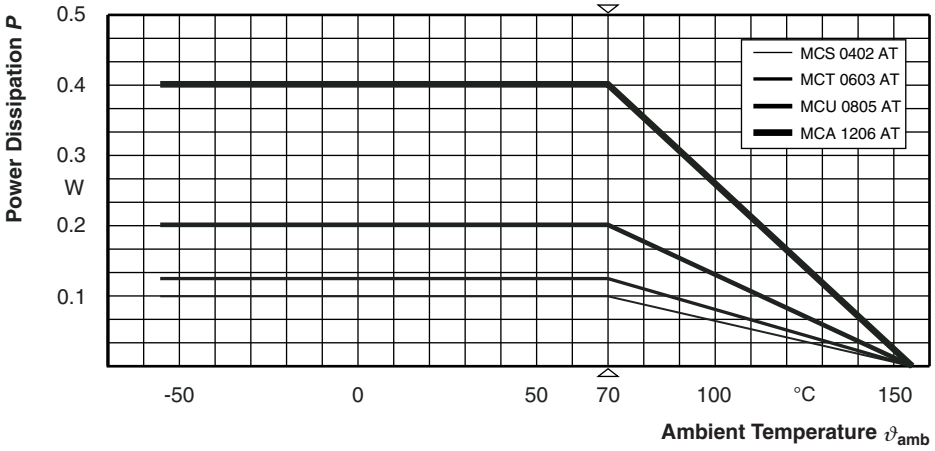
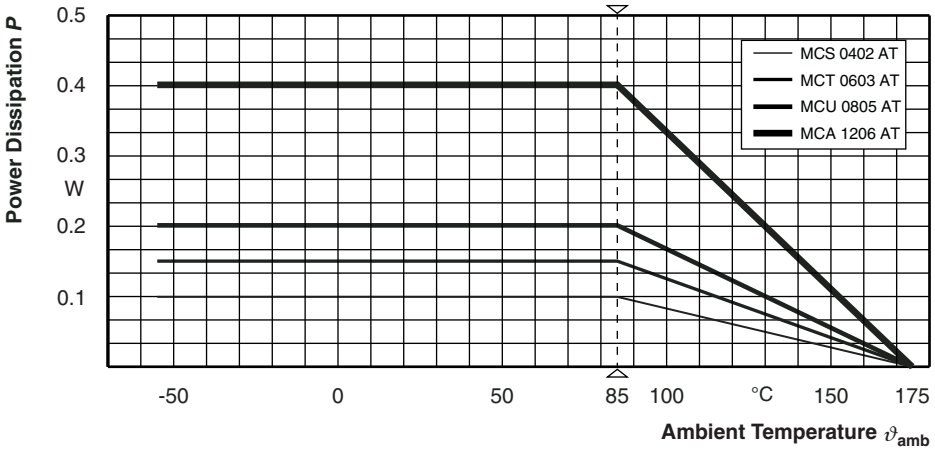
FUNCTIONAL PERFORMANCE



Derating - Standard Operation



Derating - Power Operation



Derating - Advanced Power Operation

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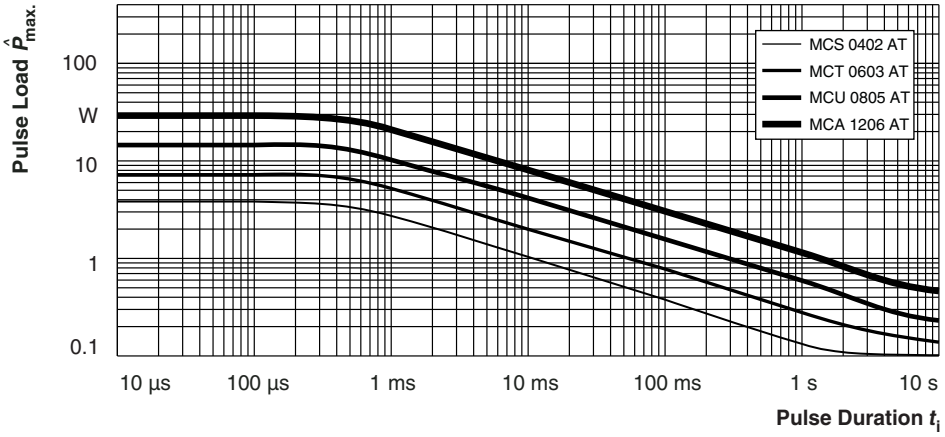
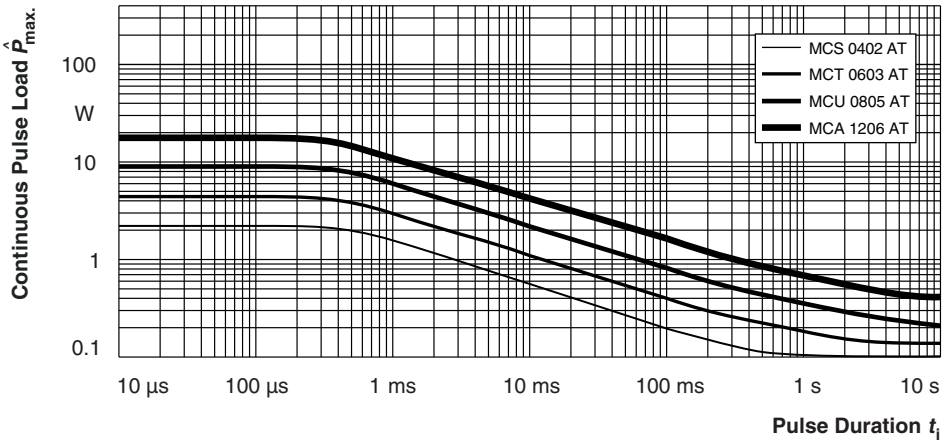
FUNCTIONAL PERFORMANCE



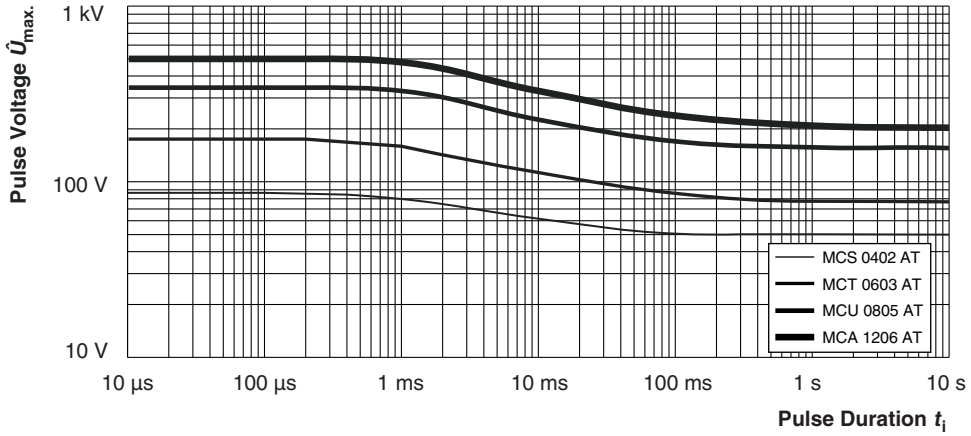
Maximum pulse load, single pulse; applicable if $\bar{P} \rightarrow 0$ and n ≤ 1000 and $\hat{U} \leq \hat{U}_{max.}$;
for permissible resistance change equivalent to 8000 h operation in standard operation mode

Single Pulse



Maximum pulse load, continuous pulses; applicable if $\bar{P} \leq P(\vartheta_{amb})$ and $\hat{U} \leq \hat{U}_{max.}$;
for permissible resistance change equivalent to 8000 h operation in standard operation mode

Continuous Pulse



Maximum pulse voltage, single and continuous pulses; applicable if $\hat{P} \leq \hat{P}_{max.}$;
for permissible resistance change equivalent to 8000 h operation in standard operation mode

Pulse Voltage

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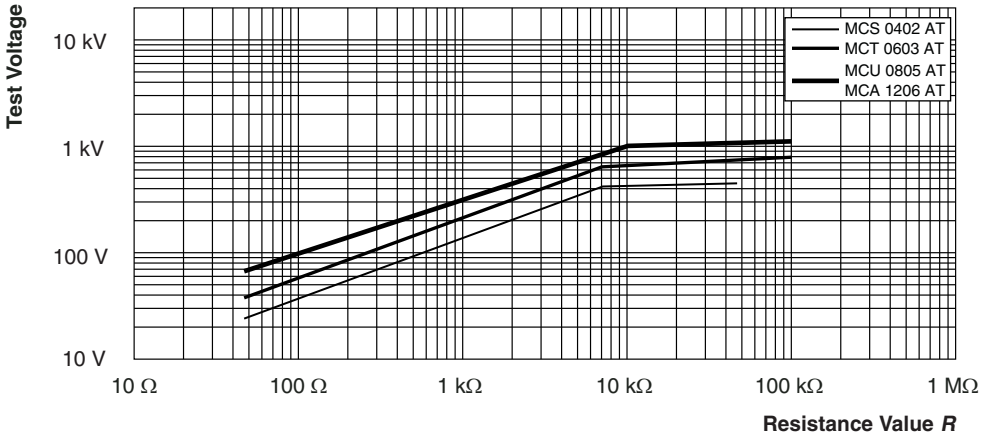
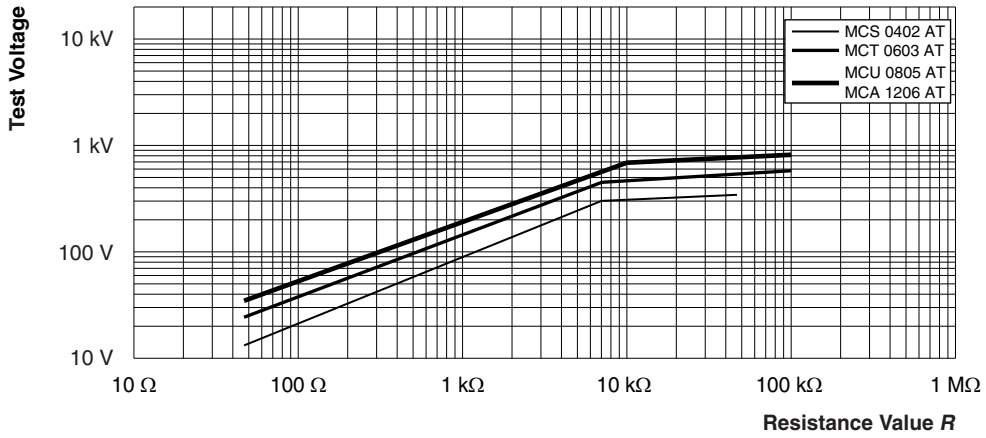


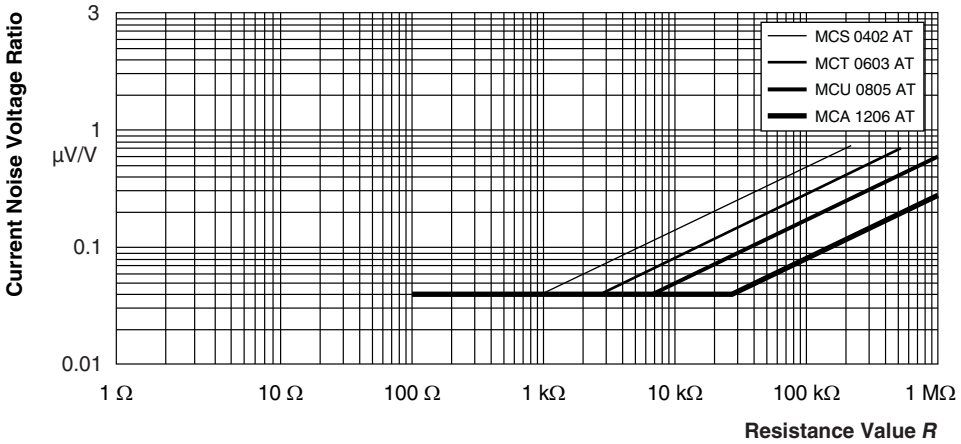
Pulse load rating in accordance with EN 60115-1 clause 4.27; 1.2 µs/50 µs; 5 pulses at 12 s interval; for permissible resistance change ± (0.5 % *R* + 0.05 Ω)

1.2/50 Pulse



Pulse load rating in accordance with EN 60115-1 clause 4.27; 10 µs/700 µs; 10 pulses at 1 min intervals; for permissible resistance change ± (0.5 % *R* + 0.05 Ω)

10/700 Pulse



In accordance with IEC 60195

Current Noise Voltage Ratio

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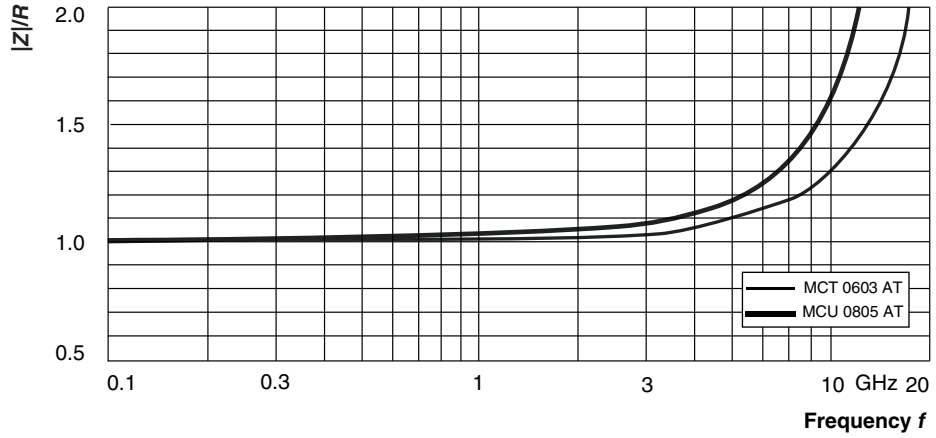

|Z|/R for 49.9 Ω chip resistor

RF-Behavior

TESTS AND REQUIREMENTS

All tests are carried out in accordance with the following specifications:

EN 60115-1, generic specification

EN 60115-8 (successor of EN 140400), sectional specification

EN 140401-801, detail specification

IEC 60068-2-xx, test methods

The components are approved under the IECQ-CECC quality assessment system for electronic components.

The parameters stated in the Test Procedures and Requirements table are based on the required tests and permitted limits of EN 140401-801. The table presents only the most important tests, for the full test schedule refer to the documents listed above. However, some additional tests and a number of improvements against those minimum requirements have been included.

The testing also covers most of the requirements specified by EIA/ECA-703 and JIS-C-5201-1.

The tests are carried out under standard atmospheric conditions in accordance with IEC 60068-1, 4.3, whereupon the following values are applied:

Temperature: 15 °C to 35 °C

Relative humidity: 25 % to 75 %

Air pressure: 86 kPa to 106 kPa (860 mbar to 1060 mbar)

A climatic category LCT / UCT / 56 is applied, defined by the lower category temperature (LCT), the upper category temperature (UCT), and the duration of exposure in the damp heat, steady state test (56 days).

The components are mounted for testing on printed circuit boards in accordance with EN 60115-8, 2.4.2, unless otherwise specified.

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TEST PROCEDURES AND REQUIREMENTS				
EN 60115-1 CLAUSE	IEC 60068-2 [1] TEST METHOD	TEST	PROCEDURE	REQUIREMENTS PERMISSIBLE CHANGE (ΔR)
				STABILITY CLASS 0.5 OR BETTER
			Stability for product types:	
			MCS 0402 AT	1 Ω to 221 kΩ
			MCT 0603 AT	1 Ω to 511 kΩ
			MCU 0805 AT	1 Ω to 1 MΩ
			MCA 1206 AT	1 Ω to 1 MΩ
4.5	-	Resistance		± 1 % R; ± 0.5 % R
4.8	-	Temperature coefficient	At (20/-55/20) °C and (20/155/20) °C	± 50 ppm/K; ± 25 ppm/K
4.25.1	-	Endurance at 70 °C: standard operation mode	$U = \sqrt{P_{70} \times R}$ or $U = U_{max.}$; whichever is the less severe; 1.5 h on; 0.5 h off; 70 °C; 1000 h 70 °C; 8000 h	± (0.15 % R + 0.05 Ω) ± (0.25 % R + 0.05 Ω)
		Endurance at 70 °C: power operation mode	$U = \sqrt{P_{70} \times R}$ or $U = U_{max.}$; whichever is the less severe; 1.5 h on; 0.5 h off; 70 °C; 1000 h 70 °C; 8000 h	± (0.3 % R + 0.05 Ω) ± (0.5 % R + 0.05 Ω)
		Endurance at 85 °C: advanced temperature operation mode	$U = \sqrt{P_{85} \times R}$ or $U = U_{max.}$; whichever is the less severe; 1.5 h on; 0.5 h off; 85 °C; 1000 h	± (0.5 % R + 0.05 Ω)
4.25.3	-	Endurance at upper category temperature	125 °C; 1000 h 155 °C; 1000 h 175 °C; 1000 h	± (0.15 % R + 0.05 Ω) ± (0.3 % R + 0.05 Ω) ± (0.5 % R + 0.05 Ω)
4.24	78 (Cab)	Damp heat, steady state	(40 ± 2) °C; 56 days; (93 ± 3) % RH	± (0.1 % R + 0.05 Ω)
4.37	67 (Cy)	Damp heat, steady state, accelerated Standard operation mode	(85 ± 2) °C (85 ± 5) % RH $U = \sqrt{0.1 \times P_{70} \times R}$; $U \leq 0.3 \times U_{max.}$; 1000 h	± (0.5 % R + 0.05 Ω)
4.23		Climatic sequence: standard operation mode		± (0.5 % R + 0.05 Ω)
4.23.2	2 (Bb)	dry heat	155 °C; 16 h	
4.23.3	30 (Db)	damp heat, cyclic	55 °C; 24 h; ≥ 90 % RH; 1 cycle	
4.23.4	1 (Ab)	cold	-55 °C; 2 h	
4.23.5	13 (M)	low air pressure	8.5 kPa; 2 h; (25 ± 10) °C	
4.23.6	30 (Db)	damp heat, cyclic	55 °C; 24 h; ≥ 90 % RH; 5 cycles	
4.23.7	-	DC load	$U = \sqrt{P_{70} \times R} \leq U_{max.}$; 1 min	
-	1 (Aa)	Storage at low temperature	-55 °C; 2 h	± (0.1 % R + 0.01 Ω)
4.19	14 (Na)	Rapid change of temperature	30 min at -55 °C and 30 min at 155 °C; 1000 cycles	± (0.25 % R + 0.05 Ω)
		Extended rapid change of temperature	30 min at -40 °C; 30 min at 125 °C [2]; MCS 0402 AT: 3000 cycles MCT 0603 AT: 2000 cycles MCU 0805 AT: 1500 cycles MCA 1206 AT: 1000 cycles	± (0.25 % R + 0.05 Ω); (≥ 50 % of initial shear force)
4.13	-	Short time overload; standard operation mode	$U = 2.5 \times \sqrt{P_{70} \times R}$ or $U = 2 \times U_{max.}$; whichever is the less severe; 5 s	± (0.1 % R + 0.01 Ω)
		Short time overload; power operation mode		± (0.25 % R + 0.05 Ω)

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TEST PROCEDURES AND REQUIREMENTS				
EN 60115-1 CLAUSE	IEC 60068-2 [1] TEST METHOD	TEST	PROCEDURE	REQUIREMENTS PERMISSIBLE CHANGE (ΔR)
				STABILITY CLASS 0.5 OR BETTER
			Stability for product types:	
			MCS 0402 AT	1 Ω to 221 kΩ
			MCT 0603 AT	1 Ω to 511 kΩ
			MCU 0805 AT	1 Ω to 1 MΩ
			MCA 1206 AT	1 Ω to 1 MΩ
4.27	-	Single pulse high voltage overload: standard operation mode	Severity no. 4: $U = 10 \times \sqrt{P_{70} \times R}$ $U = 2 \times U_{max.}$; whichever is the less severe; 10 pulses 10 µs/700 µs	± (0.25 % R + 0.05 Ω)
		Single pulse high voltage overload: power operation mode		± (0.5 % R + 0.05 Ω)
4.39	-	Periodic electric overload: standard operation mode	$U = \sqrt{15 \times P_{70} \times R}$ $U = 2 \times U_{max.}$ whichever is the less severe; 0.1 s on; 2.5 s off; 1000 cycles	± (0.5 % R + 0.05 Ω)
		Periodic electric overload: power operation mode		± (1.0 % R + 0.05 Ω)
4.38	-	Electro static discharge (human body model)	IEC 61340-3-1 [1]; 3 pos. + 3 neg. (equivalent to MIL-STD-883, method 3015) MCS 0402 AT: 500 V MCT 0603 AT: 1000 V MCU 0805 AT: 1500 V MCA 1206 AT: 2000 V	± (0.5 % R + 0.05 Ω)
4.22	6 (Fc)	Vibration	Endurance by sweeping; 10 Hz to 2000 Hz; no resonance; amplitude ≤ 1.5 mm or ≤ 200 m/s^2; 7.5 h	± (0.1 % R + 0.01 Ω) no visible damage
4.17	58 (Td)	Solderability	Solder bath method; SnPb40; non-activated flux (215 ± 3) °C; (3 ± 0.3) s	Good tinning (≥ 95 % covered); no visible damage
			Solder bath method; SnAg3Cu0.5 or SnAg3.5; non-activated flux; (235 ± 3) °C; (2 ± 0.2) s	Good tinning (≥ 95 % covered); no visible damage
4.18	58 (Td)	Resistance to soldering heat	Solder bath method; (260 ± 5) °C; (10 ± 1) s	± (0.1 % R + 0.01 Ω) no visible damage
4.29	45 (XA)	Component solvent resistance	Isopropyl alcohol +50 °C; method 2	No visible damage
4.32	21 (Ue_3)	Shear (adhesion)	MCS 0402 AT and MCT 0603 AT; 9 N	No visible damage
			MCU 0805 AT and MCA 1206 AT; 45 N	
4.33	21 (Ue_1)	Substrate bending	Depth 2 mm, 3 times	± (0.1 % R + 0.01 Ω) no visible damage; no open circuit in bent position
4.7	-	Voltage proof	$U_{RMS} = U_{ins}$; (60 ± 5) s	No flashover or breakdown
4.35	-	Flammability	IEC 60695-11-5 [1] needle flame test; 10 s	No burning after 30 s

Notes

[1] The quoted IEC standards are also released as EN standards with the same number and identical contents

[2] Tested on a 4-layer printed circuit board with SAC micro alloy

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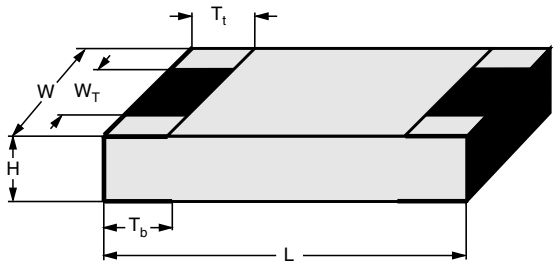
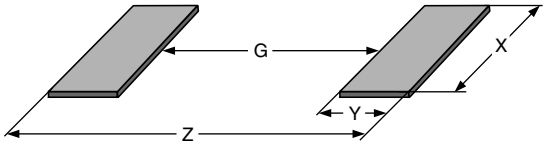
DIMENSIONS



DIMENSIONS AND MASS							
TYPE / SIZE	H (mm)	L (mm)	W (mm)	W_T (mm)	T_t (mm)	T_b (mm)	MASS (mg)
MCS 0402 AT	0.32 ± 0.05	1.0 ± 0.05	0.5 ± 0.05	> 75 % of W	0.2 + 0.1/- 0.15	0.2 ± 0.1	0.6
MCT 0603 AT	0.45 + 0.1/- 0.05	1.55 ± 0.05	0.85 ± 0.1	> 75 % of W	0.3 + 0.15/- 0.2	0.3 + 0.15/- 0.2	1.9
MCU 0805 AT	0.52 ± 0.1	2.0 ± 0.1	1.25 ± 0.15	> 75 % of W	0.4 + 0.1/- 0.2	0.4 + 0.1/- 0.2	4.6
MCA 1206 AT	0.55 ± 0.1	3.2 + 0.1/- 0.2	1.6 ± 0.15	> 75 % of W	0.5 ± 0.25	0.5 ± 0.25	9.2

SOLDER PAD DIMENSIONS



RECOMMENDED SOLDER PAD DIMENSIONS								
TYPE / SIZE	WAVE SOLDERING				REFLOW SOLDERING			
	G (mm)	Y (mm)	X (mm)	Z (mm)	G (mm)	Y (mm)	X (mm)	Z (mm)
MCS 0402 AT	-	-	-	-	0.35	0.55	0.55	1.45
MCT 0603 AT	0.55	1.10	1.10	2.75	0.65	0.70	0.95	2.05
MCU 0805 AT	0.80	1.25	1.50	3.30	0.90	0.90	1.40	2.70
MCA 1206 AT	1.40	1.50	1.90	4.40	1.50	1.15	1.75	3.80

Notes

- The given solder pad dimensions reflect the considerations for board design and assembly as outlined e.g. in standards IEC 61188-5-x [(1)], or in publication IPC-7351

[(1)] The quoted IEC standards are also released as EN standards with the same number and identical contents

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